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5. A method of manufacturing an electronic part according to claim 4, characterized in that a thickness of the thin film insulating layer is between 1 to 15  $\mu\text{m}$ .

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6. A method of manufacturing an electronic part according to any one of claims 1 to 5, characterized in that the columnar conductor is formed by a metal plating process.

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7. (Deleted)

8. (Deleted)